

**• General Description**

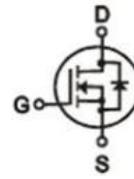
It combines trench MOSFET technology with a low resistance package to provide extremely low  $R_{DS(ON)}$ . This device is ideal for motor driver, load switch and battery protection applications.

**• Features**

- Low  $R_{DS(ON)}$  to minimize conductive loss
- Low Gate Charge for fast switching
- Low Thermal resistance

**• Application**

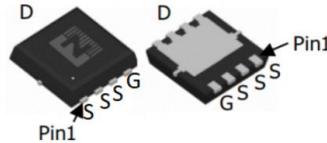
- BLDC Motor driver
- SMPS 2nd Synchronous Rectifier
- Battery protection

**• Product Summary**


$V_{DS}=40V$

$R_{DS(ON)}=8m\Omega$

$I_D=35A$



DFN3 x 3

**• Ordering Information:**

Part NO.	ZM074N04M
Marking	074N04
Packing Information	REEL TAPE
Basic ordering unit (pcs)	5000

**• Absolute Maximum Ratings (T<sub>C</sub>=25°C)**

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	$V_{DS}$	40	V
Gate-Source Voltage	$V_{GS}$	±20	V
Continuous Drain Current	$I_D@T_C=25^\circ C$	35	A
	$I_D@T_C=75^\circ C$	26	A
	$I_D@T_C=100^\circ C$	22	A
Pulsed Drain Current <sup>①</sup>	$I_{DM}$	105	A
Total Power Dissipation	$P_D@T_C=25^\circ C$	43	W
Total Power Dissipation	$P_D@T_A=25^\circ C$	2.3	W
Operating Junction Temperature	$T_J$	-55 to 150	°C
Storage Temperature	$T_{STG}$	-55 to 150	°C
Single Pulse Avalanche Energy (L=0.1mH, V <sub>GS</sub> =10V, R <sub>g</sub> =25Ω, T <sub>J</sub> =25°C)	$E_{AS}$	40	mJ
ESD Level (HBM)		Class 1C	

**•Thermal resistance**

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal resistance, junction - case	$R_{thJC}$	-	-	2.9	$^{\circ}C/W$
Thermal resistance, junction - ambient <sup>②</sup>	$R_{thJA}$	-	-	54	$^{\circ}C/W$
Soldering temperature, wave soldering for 10s	$T_{sold}$	-	-	260	$^{\circ}C$

**•Electronic Characteristics**

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	40			V
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}, I_D = 250\mu A$	1.4		2.5	V
Drain-Source Leakage Current	$I_{DSS}$	$V_{DS} = 40V, V_{GS} = 0V$			1.0	$\mu A$
Gate- Source Leakage Current	$I_{GSS}$	$V_{GS} = \pm 20V, V_{DS} = 0V$			$\pm 100$	nA
Static Drain-source On Resistance	$R_{DS(ON)}$	$V_{GS} = 10V, I_D = 24A$		8	12	m $\Omega$
		$V_{GS} = 4.5V, I_D = 12A$		13	17	m $\Omega$
Forward Trans conductance	$g_{FS}$	$V_{DS} = 10V, I_D = 10A$		8		s
Source-drain voltage	$V_{SD}$	$I_S = 24A$			1.28	V

**•Dynamic Characteristics**

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit	
Gate Resistance	$R_G$	$f = 1MHz$		1.4		$\Omega$	
Input capacitance	$C_{iss}$	$f = 1MHz$ $V_{DS} = 25V$	-	1930	-	pF	
Output capacitance	$C_{oss}$		-	154	-		
Reverse transfer capacitance	$C_{rss}$		-	110	-		
Total gate charge	$Q_g$	$V_{DD} = 25V$ $I_D = 20A$ $V_{GS} = 10V$	-	30	-	nC	
	$Qg(4.5v)$			13			
	Gate - Source charge		$Q_{gs}$	-	5.4		-
	Gate - Drain charge		$Q_{gd}$	-	5.9		-
Turn-ON Delay time	$t_{D(on)}$	$V_{GS} = 10V, V_{DS} = 15V$ $R_G = 3.3\Omega,$ $I_D = 20A$		8		ns	
Turn-ON Rise time	$t_r$			2.5		ns	
Turn-Off Delay time	$t_{D(off)}$			41		ns	
Turn-Off Fall time	$t_f$			8		ns	
Reverse Recovery Time	$t_{RR}$	$V_{DD} = 20V, dI_S/dt$ $= 100A/s, I_S = 30A$		11		ns	
Reverse Recovery Charge	$Q_{RR}$			20		ns	

Fig.1 Power Dissipation

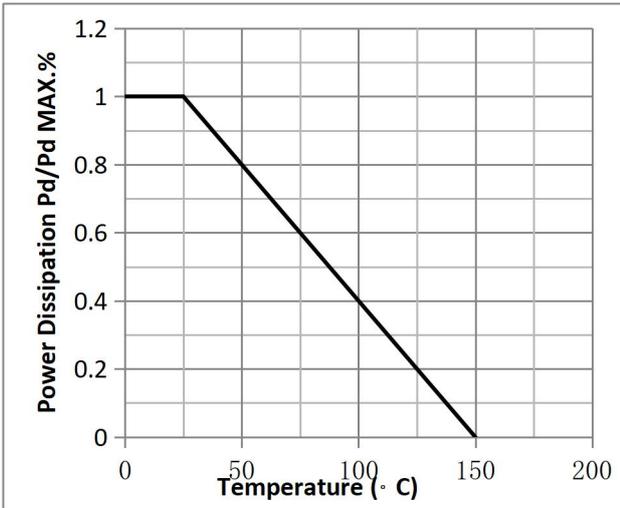


Fig.2 Typical output Characteristics

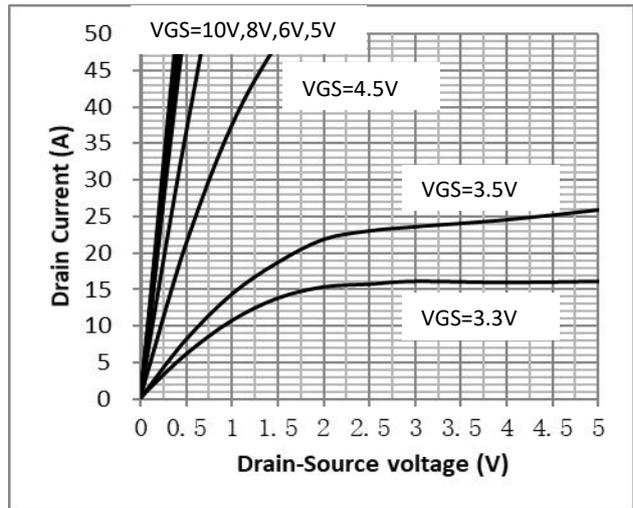


Fig.3 Threshold Voltage V.S Junction Temperature

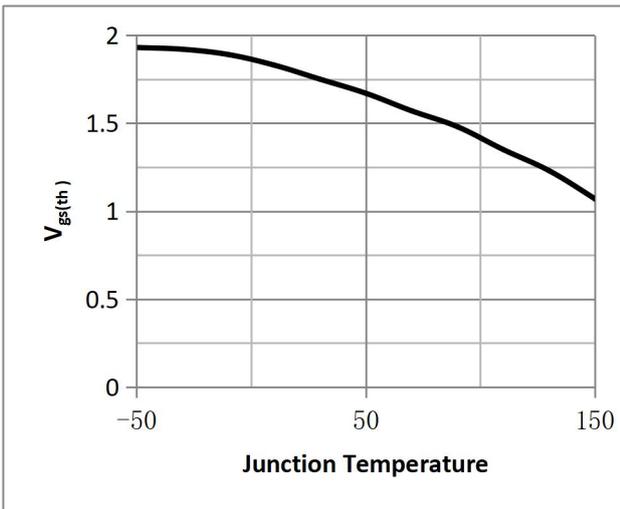


Fig.4 Resistance V.S Drain Current

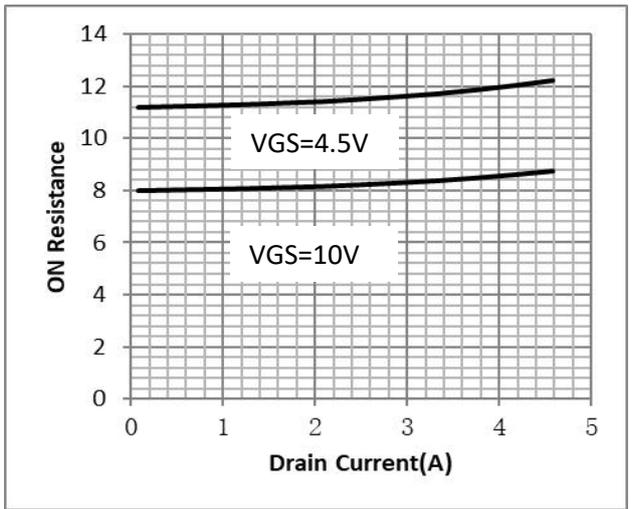


Fig.5 On-Resistance VS Gate Source Voltage

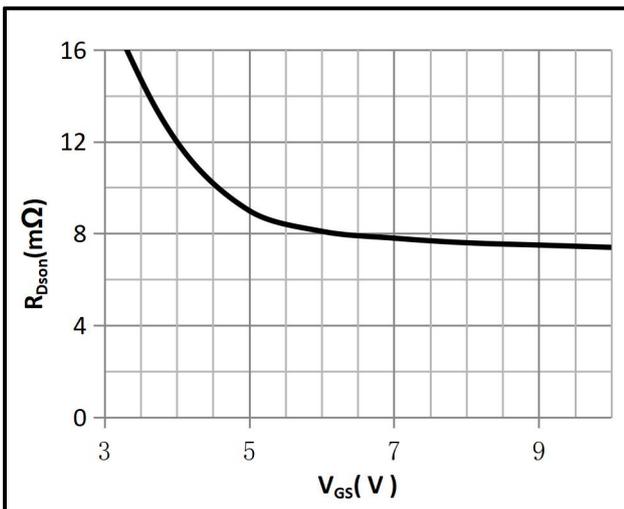


Fig.6 On-Resistance V.S Junction Temperature

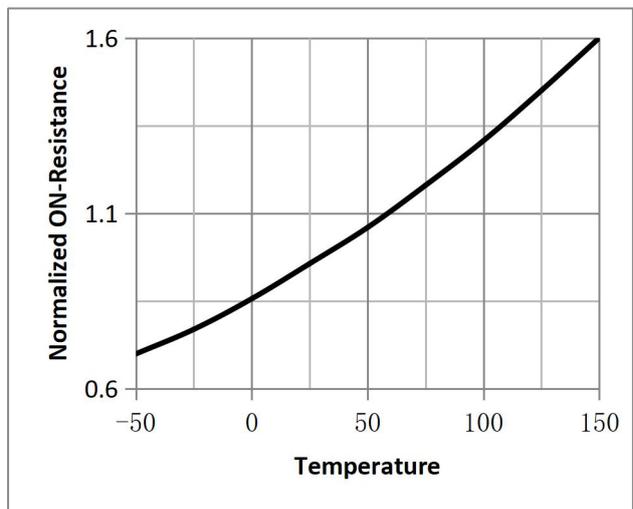


Fig.7 SOA Maximum Safe Operating Area

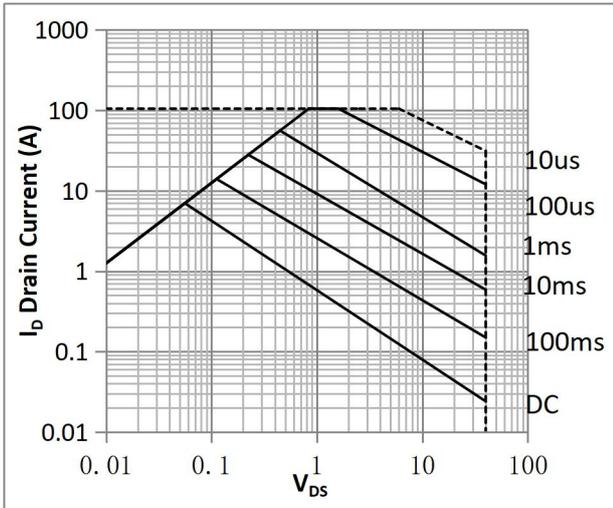


Fig.8 ID-Junction Temperature

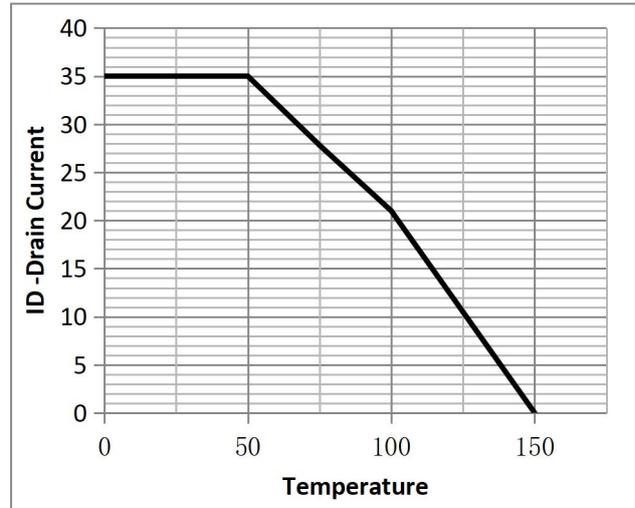


Figure 9. Diode Forward Voltage vs. Current

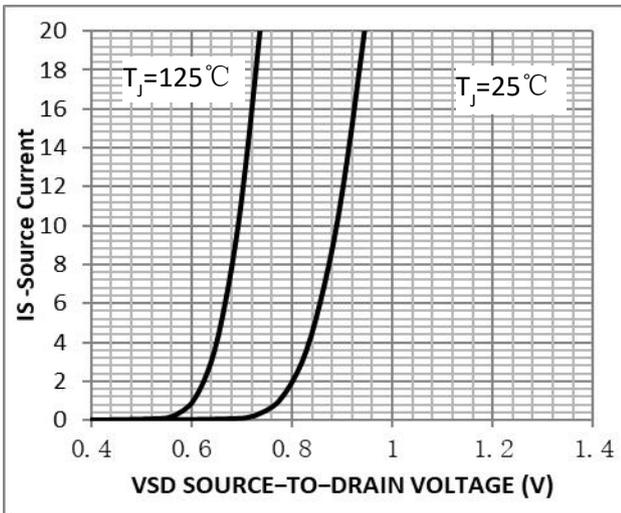


Figure 10. Transfer Characteristics

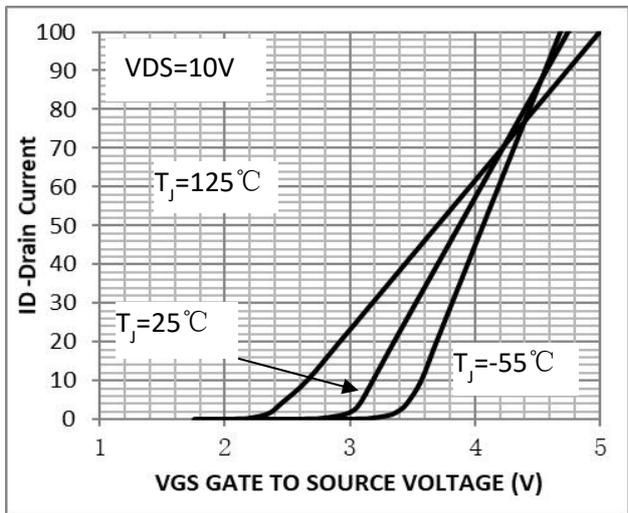


Figure 11. Gate-to-Source and Drain-to-Source Voltage vs. Total Charge

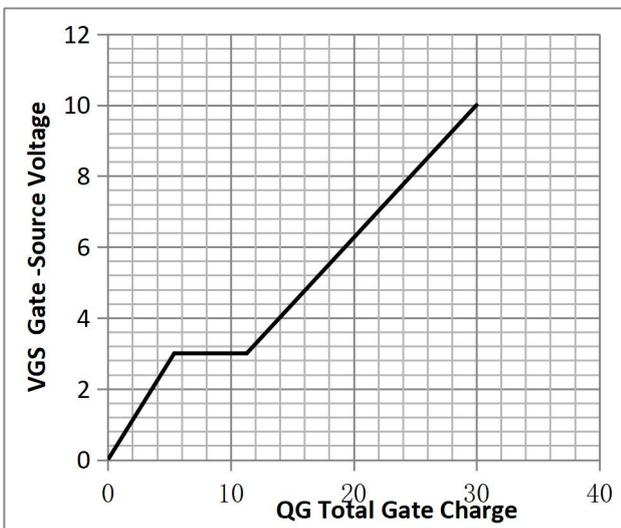


Fig.12 Capacitance Variation

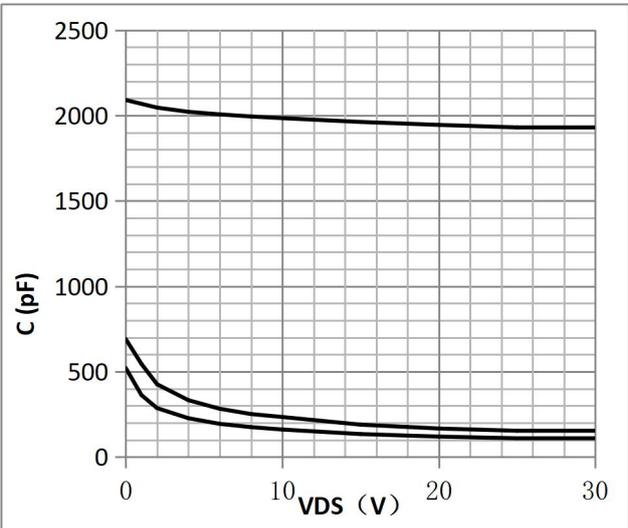


Fig.13 Switching Time Measurement Circuit

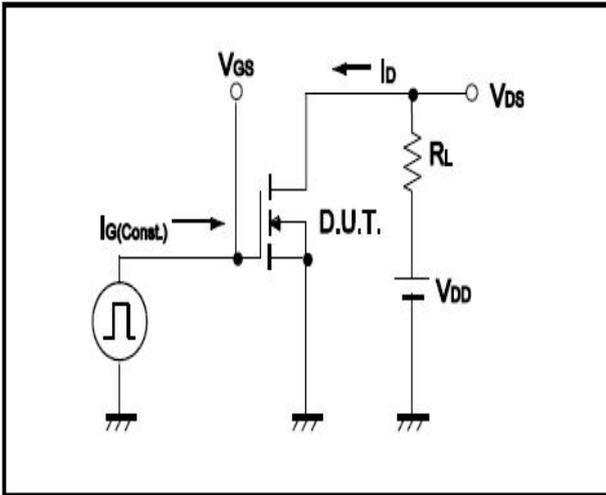


Fig.14 Gate Charge Waveform

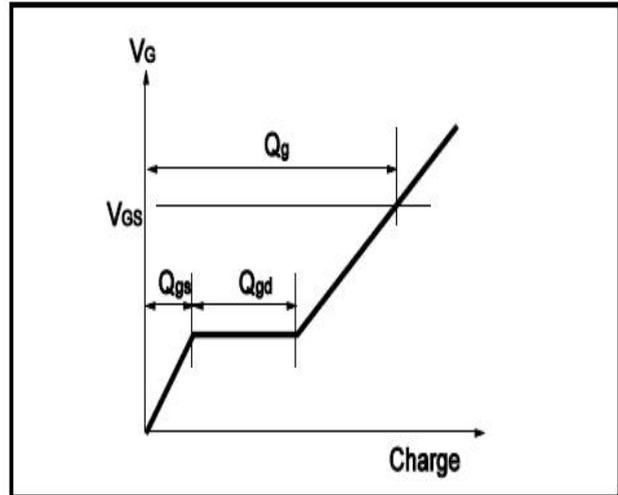


Fig.15 Switching Time Measurement Circuit

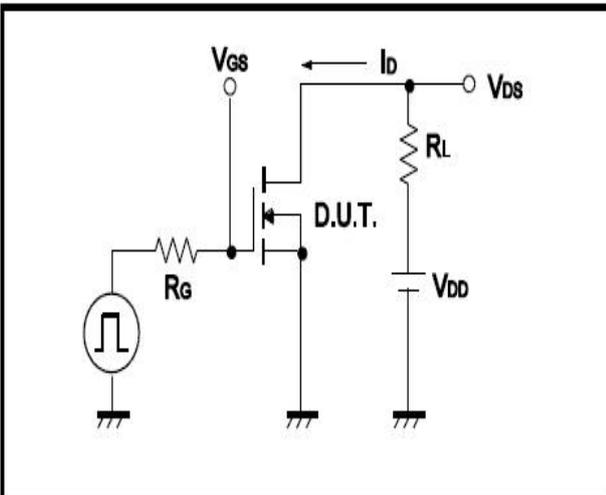


Fig.16 Gate Charge Waveform

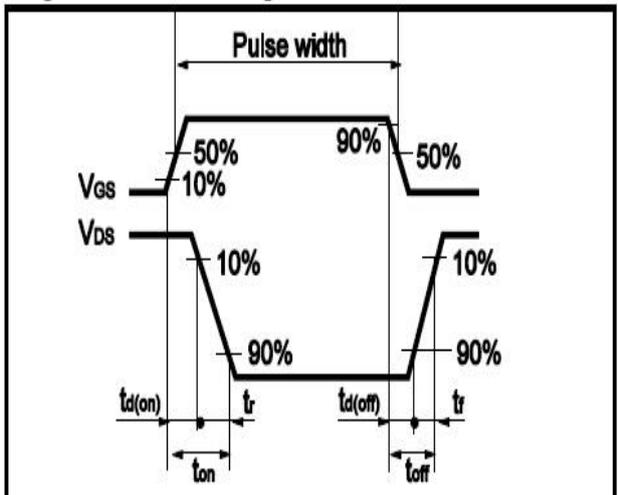


Fig.17 Avalanche Measurement Circuit

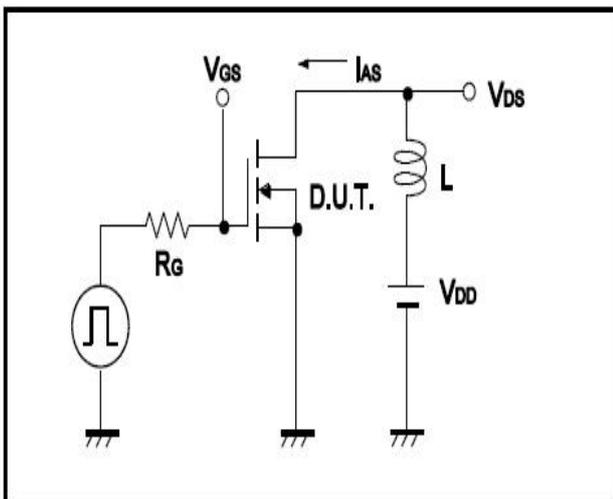
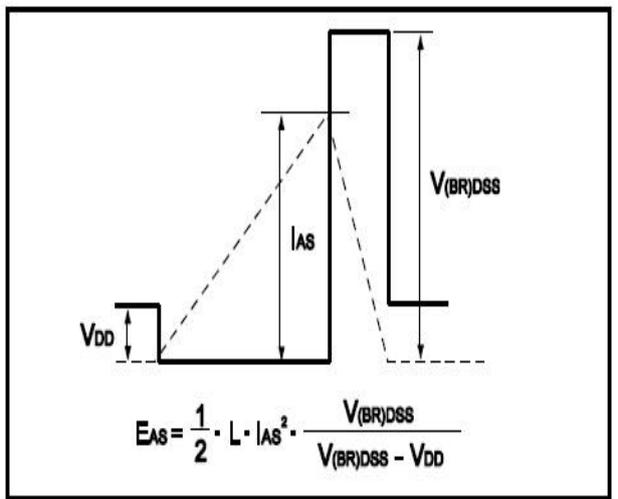


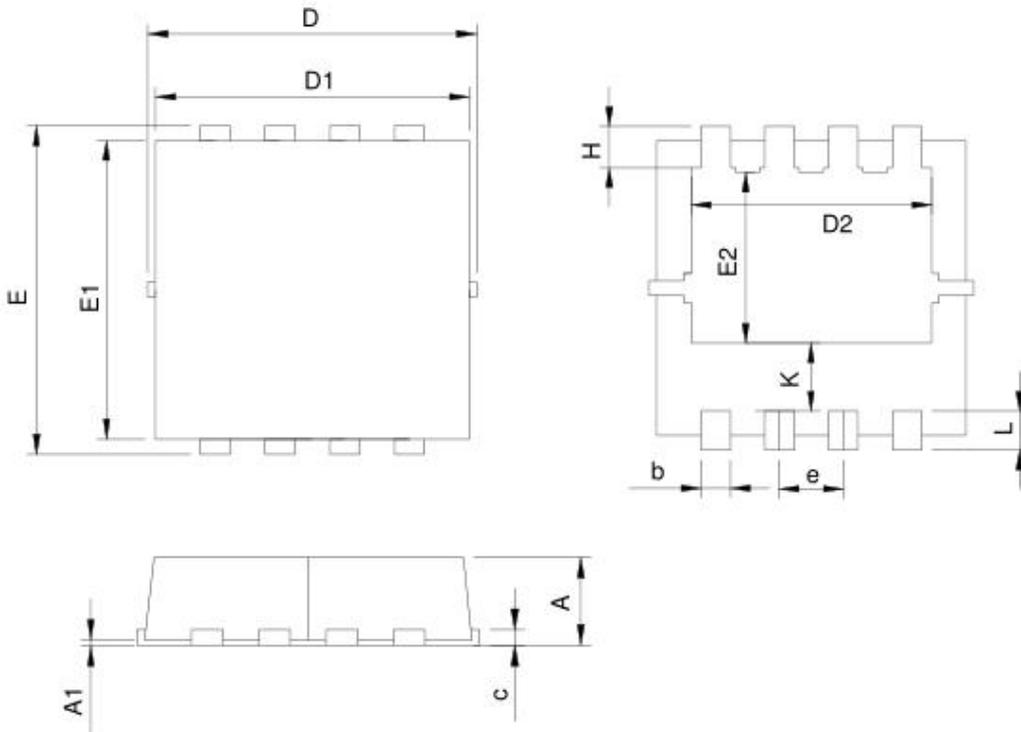
Fig.18 Avalanche Waveform





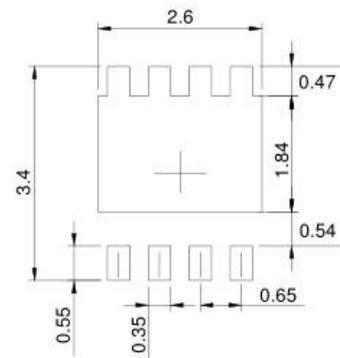
•Dimensions(DFN3×3)

Unit: mm



SYMBOL	DFN3.3x3.3-8			
	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	0.70	1.00	0.028	0.039
A1	0.00	0.05	0.000	0.002
b	0.25	0.35	0.010	0.014
c	0.14	0.20	0.006	0.008
D	3.10	3.50	0.122	0.138
D1	3.05	3.25	0.120	0.128
D2	2.35	2.55	0.093	0.100
E	3.10	3.50	0.122	0.138
E1	2.90	3.10	0.114	0.122
E2	1.64	1.84	0.065	0.072
e	0.65 BSC		0.026 BSC	
H	0.32	0.52	0.013	0.020
K	0.59	0.79	0.023	0.031
L	0.25	0.55	0.010	0.022

RECOMMENDED LAND PATTERN



UNIT: mm



Note: ① Pulse Test: Pulse width  $\leq 300\mu\text{s}$ , Duty cycle  $\leq 2\%$  ;

② Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1inch square copper plate;

Disclaimer

- Reproducing and modifying information of the document is prohibited without permission from ZMJ SEMICONDDUCTORS CO.,LTD.
- ZMJ SEMICONDDUCTORS CO.,LTD. reserves the rights to make changes of the content herein the document anytime without notification. Please refer to our website for the latest document.
- ZMJ SEMICONDDUCTORS CO.,LTD. disclaims any and all liability arising out of the application or use of any product including damages incidentally and consequentially occurred.
- ZMJ SEMICONDDUCTORS CO.,LTD. does not assume any and all implied warranties, including warranties of fitness for particular purpose, non-infringement and merchantability.
- Applications shown on the herein document are examples of standard use and operation. Customers are responsible in comprehending the suitable use in particular applications. ZMJ SEMICONDDUCTORS CO.,LTD. makes no representation or warranty that such applications will be suitable for the specified use without further testing or modification.
- The products shown herein are not designed and authorized for equipments relating to human life and for any applications concerning life-saving or life-sustaining, such as medical instruments, aerospace machinery et cetera. Customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify ZMJ SEMICONDDUCTORS CO.,LTD. for any damages resulting from such improper use or sale.
- Since ZMJ uses lot number as the tracking base, please provide the lot number for tracking when complaining.